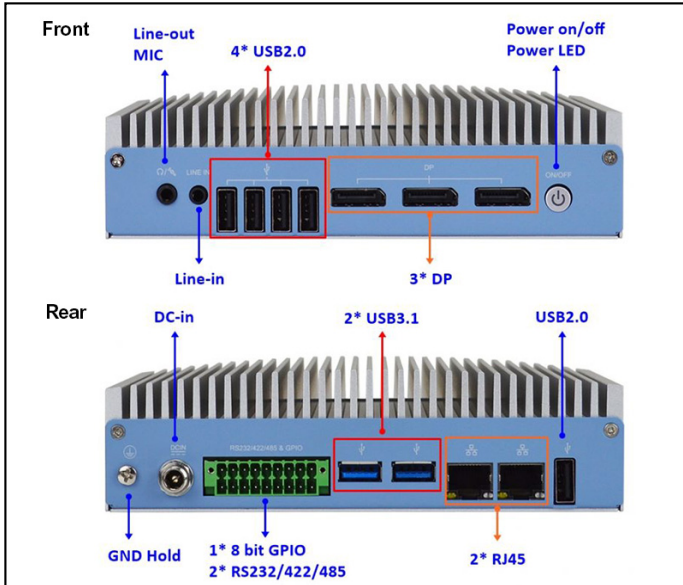


Fanless embedded system with Intel® J6412 processor supports DC-in 12~36V and wide temperature range 20°C ~ 70°C



Features

- **Efficient Processing:** Powered by Intel® J6412 SoC Processor (Elkhart Lake, TDP 10W)
- **Triple Display Support:** Equipped with 3 x DisplayPort outputs supporting 4K resolution
- **Comprehensive I/O:** Includes 2 x USB 3.2 Gen2, 4 x USB 2.0, and 1 Phoenix Port (1 GPIO, 2 RS232/422/485)
- **Storage & Expansion:** Optional eMMC, 1 x M.2 E-Key, 1 x M.2 M-Key, 1 x M.2 B-Key, and 1 SIM card slot
- **Compact Fanless Design:** Supports Wall Mount and DIN Rail for Space-Saving Installation
- **Wide Range DC-In:** Supports 12~36V input for versatile power options

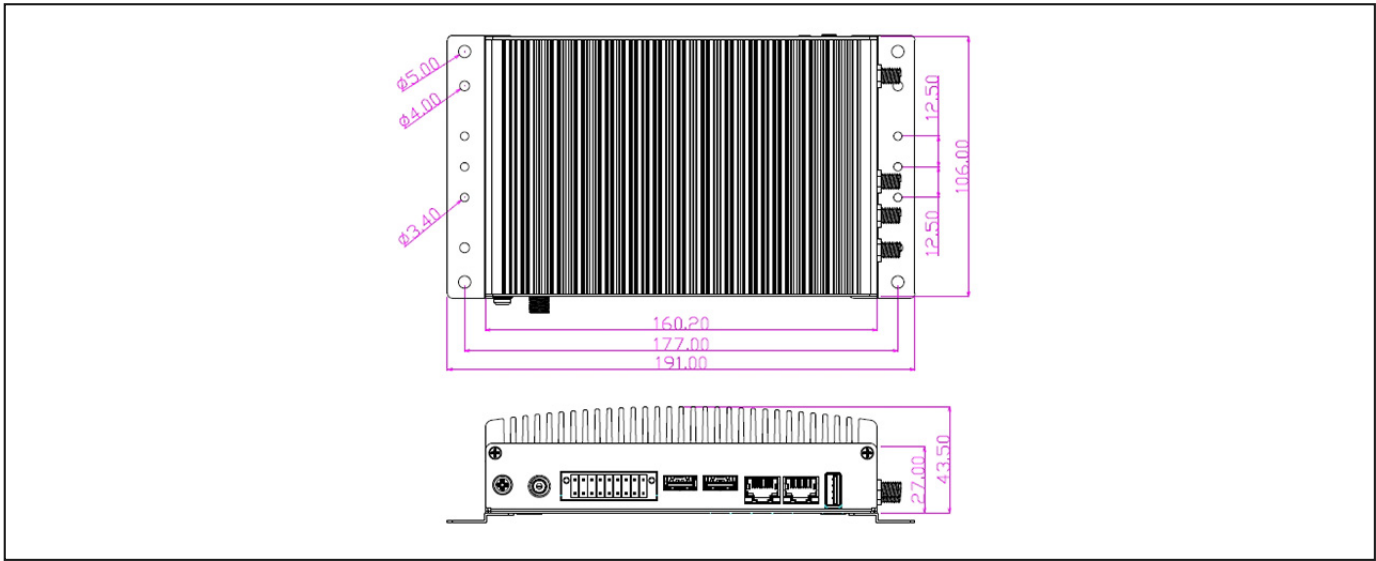
Packing List

PART NUMBER	DESCRIPTION	QTY
HB368F21-6412-W Series	HB368F21-6412-W Series	1
HCSFBMWM01B-F	WALL MOUNT KITS	1
HCS3XDINRAILPS-F	DIN RAIL KITS	1
L01AS052-F	Adapter DC12V_60W	1
Change according to shipping area	Power Cord	1
LCSCHJC3XX-F	Screw Pack	1
J05-ANT-GX57245-F	Antenna 2G4/5G 2.8dBi (WiFi only)	1

Specifications

SYSTEM	
MB FORM FACTOR	Performance
CPU	Onboard Intel® Celeron® Processor J6412 (Formerly Elkhart Lake, TDP 10W) For additional compatible CPUs, please contact regional sales
CHIPSET	Intel® SoC
MEMORY	1 x DDR4 3200MHz, Single Channel SO-DIMM, up to 32GB
BIOS	AMI Flash ROM
WATCHDOG TIMER	255 Levels
SECURITY	TPM2.0
OS SUPPORT	Windows® 11 (64bit) Windows® 10 (64bit) Linux
POWER	
POWER REQUIREMENT	DC-in 12~36V 40W Adapter: AC90~240V, DC12V/3.3A
POWER ON MODE	AT / ATX
DISPLAY	
GPU	Intel® HD Graphics, shared memory
DP	3 x DP (Max Resolution: 4096*2160@60Hz)
MULTIPLE DISPLAY	Support 3 Displays
LAN	
ETHERNET	2 x RJ45 for Realtek® RTL81191 GbE
SYSTEM I/O	
REAR PANEL I/O	2 x RJ45 2 x USB 3.1 Gen.2 1 x USB 2.0 1 x 8-bit GPIO (Phoenix Connector 2 x 9 PIN) 2 x RS-232/422/485 (Phoenix Connector 2 x 9 PIN) 1 x DC-in 1 x GND Hold
FRONT PANEL I/O	1 x Power Button + Power LED 4 x USB 2.0 1 x Audio (Line-out + MIC-in) 1 x Line-in 3 x DP
STORAGE	
eMMC	eMMC 64GB (optional)
EXPANSION	
M.2	1 x M-Key 2242/2280 (SATA III/PCIe 3.0 x2) Support NVMe 1 x E-Key 2230 (USB 2.0/PCIe 3.0 x1) 1 x B-key 3042 (USB3.0 interface)
SIM	1 x SIM Card Slot
MECHANICAL	
MOUNTING	Wall Mount, DIN Rail Clip
DIMENSIONS (W x H x D)	160.2 (W) x 106.0 (D) x 43.5 (H) mm
GROSS WEIGHT	1.52 kg
NET WEIGHT	1.01 kg
ENVIRONMENT & CERTIFICATION	
SHOCK	15G, 11ms duration
VIBRATION	1 Grms/ 5~ 500Hz/ Operation
OPERATING TEMPERATURE	-20°C ~ 70°C (-4°F ~ 158°F)
STORAGE TEMPERATURE	-40°C ~ 85°C (-40°F ~ 185°F)
OPERATING HUMIDITY	10 ~ 90% Relative Humidity, Non-condensing
STORAGE HUMIDITY	0 ~ 95% Relative Humidity, Non-condensing
CERTIFICATION	CE/FCC Class A LVD
ESG DECLARATION	EU RoHS China RoHS ErP

Dimension Unit: mm



Ordering Information

PART NUMBER	HB368F21-6412-W	HB368F21I-6412-W
CPU	Intel® Celeron® J6412	Intel® Celeron® J6412
POWER REQUIREMENT	DC-in 12-36V	DC-in 12-36V
GPU	Intel® HD Graphics, shared memory	Intel® HD Graphics, shared memory
DP	3 x DP (Max Resolution: 4096*2160@60Hz)	3 x DP (Max Resolution: 4096*2160@60Hz)
MULTIPLE DISPLAY	Support 3 Displays	Support 3 Displays
ETHERNET	2 x GbE	2 x GbE
I/O	2 x RJ45	2 x RJ45
I/O	2 x USB 3.2 Gen 2	2 x USB 3.2 Gen 2
I/O	5 x USB 2.0	5 x USB 2.0
I/O	2 x RS-232/422/485	2 x RS-232/422/485
I/O	1 x GPIO	1 x GPIO
I/O	1 x DC Jack	1 x DC Jack
I/O	1 x Power Button	1 x Power Button
I/O	1 x Power LED	1 x Power LED
I/O	1 x Audio (Line-out, MIC)	1 x Audio (Line-out, MIC)
I/O	1 x Line-in	1 x Line-in
M.2	1 x M-Key 2242/2280	1 x M-Key 2242/2280
M.2	1 x E-Key 2230	1 x E-Key 2230
M.2	1 x B-Key 3042	1 x B-Key 3042
OTHER		WiFi
OPERATING TEMPERATURE	-20°C - 70°C (-4°F - 158°F)	-20°C - 70°C (-4°F - 158°F)